



Material Content Data Sheet



Sales Product Name				KP216K1409		Issued		29. August 2013	
MA#				MA000872316					
Package				PG-DSOF-8-16		Weight*		227.16 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.899	5.68	5.68	56781	56781	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.00		41		
	non noble metal	zinc	7440-66-6	0.037	0.02		163		
	non noble metal	iron	7439-89-6	0.740	0.33		3256		
wire	non noble metal	copper	7440-50-8	30.034	13.22	13.57	132212	135672	
	noble metal	gold	7440-57-5	0.178	0.08	0.08	782	782	
	encapsulation	organic material	carbon black	1333-86-4	0.588	0.26		2587	
encapsulation	plastics	silicone resin	-	17.373	7.65		76479		
	plastics	epoxy resin	-	21.305	9.38		93785		
	inorganic material	silicondioxide	60676-86-0	125.036	55.03	72.32	550423	723274	
leadfinish	noble metal	gold	7440-57-5	0.020	0.01		87		
	non noble metal	nickel	7440-02-0	0.196	0.09		863		
	inorganic material	phosphorus	7723-14-0	0.000	0.00		2		
plating	noble metal	palladium	7440-05-3	0.020	0.01	0.11	88	1040	
	inorganic material	chromiumoxide	1308-38-9	0.170	0.08		750		
	inorganic material	zincoxide	1314-13-2	0.397	0.17	0.25	1749	2499	
glue	inorganic material	alumina	1344-28-1	0.159	0.07		700		
	inorganic material	thalliumtrioxid	1314-12-1	0.029	0.01		127		
	inorganic material	silicondioxide	60676-86-0	0.535	0.24		2354		
lid	plastics	silicone resin	-	2.168	0.95	1.27	9544	12725	
	inorganic material	glass fibre	-	5.716	2.52		25163		
	plastics	Polyphenylene Sulfide	26125-40-6	8.574	3.77	6.29	37744	62907	
lid attach material	organic material	carbon black	1333-86-4	0.005	0.00		22		
	inorganic material	silicondioxide	60676-86-0	0.476	0.21		2095		
	plastics	epoxy resin	-	0.500	0.22	0.43	2203	4320	
*deviation	< 10%		Sum in total:			100,00		1000000	

Important Remarks:

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